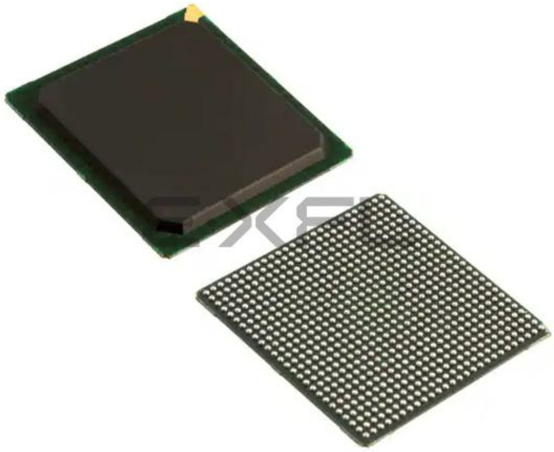
Microchip Technology - A3PE1500-2FGG676 Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	276480
Number of I/O	444
Number of Gates	1500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3pe1500-2fgg676

ProASIC3E Ordering Information

A3PE3000 – 1 FG G 896 I Y

Security Feature
Y = Device Includes License to Implement IP Based on the Cryptography Research, Inc. (CRI) Patent Portfolio
Note: *Only devices with packages greater than or equal to 5x5 are supported*
Blank = Device Does Not Include License to Implement IP Based on the Cryptography Research, Inc. (CRI) Patent Portfolio

Application (Temperature Range)
Blank = Commercial (0°C to +85°C Junction Temperature)
I = Industrial (–40°C to +100°C Junction Temperature)
PP = Pre-Production
ES = Engineering Sample (Room Temperature Only)

Package Lead Count

Lead-Free Packaging
Blank = Standard Packaging
G = RoHS-Compliant (Green) Packaging

Package Type
PQ = Plastic Quad Flat Pack (0.5 mm pitch)
FG = Fine Pitch Ball Grid Array (1.0 mm pitch)

Speed Grade
1 = 15% Faster than Standard
2 = 25% Faster than Standard

Part Number

ProASIC3E Devices

A3PE600 = 600,000 System Gates
A3PE1500 = 1,500,000 System Gates
A3PE3000 = 3,000,000 System Gates

ProASIC3E Devices with Cortex-M1

M1A3PE1500 = 1,500,000 System Gates
M1A3PE3000 = 3,000,000 System Gates

Table of Contents

ProASIC3E Device Family Overview

ProASIC3E DC and Switching Characteristics

Pin Descriptions and Packaging

Package Pin Assignments

Datasheet Information

SRAM and FIFO

ProASIC3E devices have embedded SRAM blocks along their north and south sides. Each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are 256×18, 512×9, 1k×4, 2k×2, and 4k×1 bits. The individual blocks have independent read and write ports that can be configured with different bit widths on each port. For example, data can be sent through a 4-bit port and read as a single bitstream. The embedded SRAM blocks can be initialized via the device JTAG port (ROM emulation mode) using the UJTAG macro.

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using additional core VersaTiles. The FIFO width and depth are programmable. The FIFO also features programmable Almost Empty (AEMPTY) and Almost Full (AFULL) flags in addition to the normal Empty and Full flags. The embedded FIFO control unit contains the counters necessary for generation of the read and write address pointers. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

PLL and CCC

ProASIC3E devices provide designers with very flexible clock conditioning capabilities. Each member of the ProASIC3E family contains six CCCs, each with an integrated PLL.

The six CCC blocks are located at the four corners and the centers of the east and west sides.

To maximize user I/Os, only the center east and west PLLs are available in devices using the PQ208 package. However, all six CCC blocks are still usable; the four corner CCCs allow simple clock delay operations as well as clock spine access.

The inputs of the six CCC blocks are accessible from the FPGA core or from one of several inputs located near the CCC that have dedicated connections to the CCC block.

The CCC block has these key features:

- Wide input frequency range (f_{IN_CCC}) = 1.5 MHz to 350 MHz
- Output frequency range (f_{OUT_CCC}) = 0.75 MHz to 350 MHz
- Clock delay adjustment via programmable and fixed delays from –7.56 ns to +11.12 ns
- 2 programmable delay types for clock skew minimization
- Clock frequency synthesis

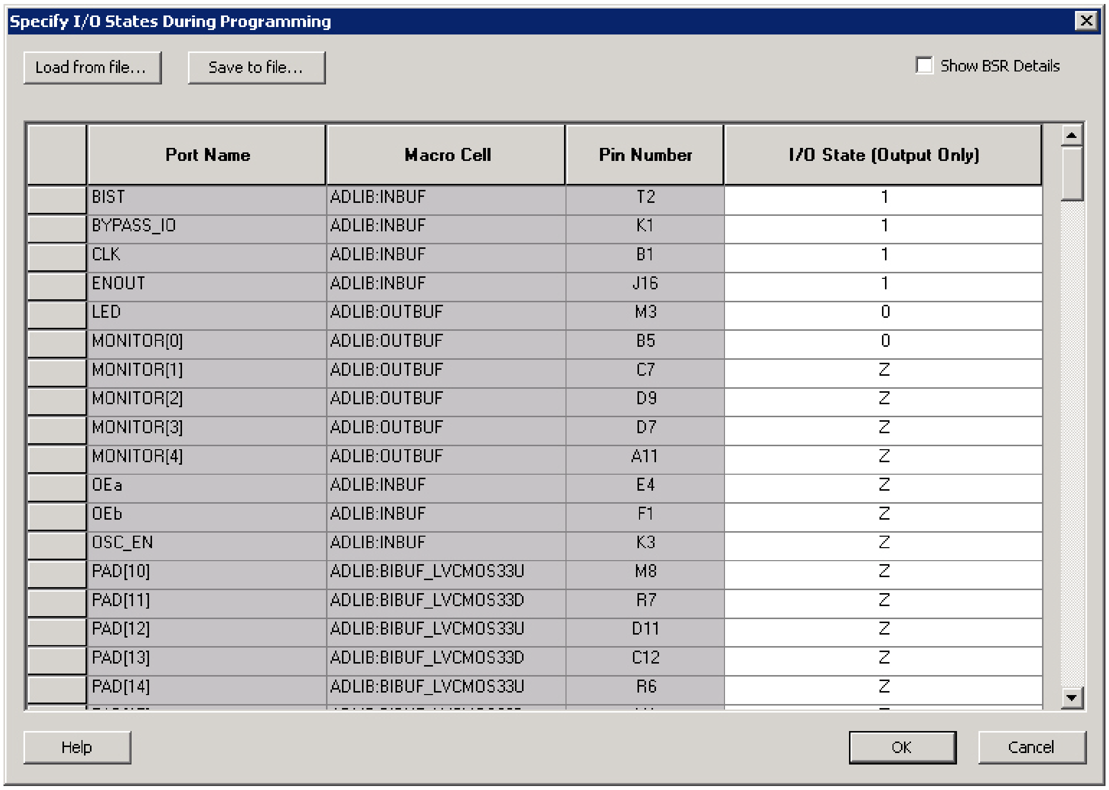
Additional CCC specifications:

- Internal phase shift = 0°, 90°, 180°, and 270°. Output phase shift depends on the output divider configuration.
- Output duty cycle = 50% ± 1.5% or better
- Low output jitter: worst case < 2.5% × clock period peak-to-peak period jitter when single global network used
- Maximum acquisition time = 300 µs
- Low power consumption of 5 mW
- Exceptional tolerance to input period jitter— allowable input jitter is up to 1.5 ns
- Four precise phases; maximum misalignment between adjacent phases of 40 ps × (350 MHz / f_{OUT_CCC})

Global Clocking

ProASIC3E devices have extensive support for multiple clocking domains. In addition to the CCC and PLL support described above, there is a comprehensive global clock distribution network.

Each VersaTile input and output port has access to nine VersaNets: six chip (main) and three quadrant global networks. The VersaNets can be driven by the CCC or directly accessed from the core via multiplexers (MUXes). The VersaNets can be used to distribute low-skew clock signals or for rapid distribution of high fanout nets.



Port Name	Macro Cell	Pin Number	I/O State (Output Only)
BIST	ADLIB:INBUF	T2	1
BYPASS_IO	ADLIB:INBUF	K1	1
CLK	ADLIB:INBUF	B1	1
ENOUT	ADLIB:INBUF	J16	1
LED	ADLIB:OUTBUF	M3	0
MONITOR[0]	ADLIB:OUTBUF	B5	0
MONITOR[1]	ADLIB:OUTBUF	C7	Z
MONITOR[2]	ADLIB:OUTBUF	D9	Z
MONITOR[3]	ADLIB:OUTBUF	D7	Z
MONITOR[4]	ADLIB:OUTBUF	A11	Z
OEa	ADLIB:INBUF	E4	Z
OEb	ADLIB:INBUF	F1	Z
OSC_EN	ADLIB:INBUF	K3	Z
PAD[10]	ADLIB:BIBUF_LVCMOS33U	M8	Z
PAD[11]	ADLIB:BIBUF_LVCMOS33D	R7	Z
PAD[12]	ADLIB:BIBUF_LVCMOS33U	D11	Z
PAD[13]	ADLIB:BIBUF_LVCMOS33D	C12	Z
PAD[14]	ADLIB:BIBUF_LVCMOS33U	R6	Z

Figure 1-3 • **I/O States During Programming Window**

6. Click OK to return to the FlashPoint – Programming File Generator window.

   I/O States during programming are saved to the ADB and resulting programming files after completing programming file generation.

Thermal Characteristics

Introduction

The temperature variable in Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction to be higher than the ambient temperature.

EQ 1 can be used to calculate junction temperature.

$$T_J = \text{Junction Temperature} = \Delta T + T_A$$

EQ 1

where:

T_A = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient $\Delta T = \theta_{ja} * P$

θ_{ja} = Junction-to-ambient of the package. θ_{ja} numbers are located in Table 2-5.

P = Power dissipation

Package Thermal Characteristics

The device junction-to-case thermal resistivity is θ_{jc} and the junction-to-ambient air thermal resistivity is θ_{ja}. The thermal characteristics for θ_{ja} are shown for two air flow rates. The absolute maximum junction temperature is 110°C. EQ 2 shows a sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and in still air.

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. (°C)} - \text{Max. ambient temp. (°C)}}{\theta_{ja}\text{(°C/W)}} = \frac{110°\text{C} - 70°\text{C}}{13.6°\text{C/W}} = 5.88\text{ W}$$

EQ 2

Table 2-5 • **Package Thermal Resistivities**

Package Type	Pin Count	θ_{jc}	θ_{ja}			Units
			Still Air	200 ft./min.	500 ft./min.	
Plastic Quad Flat Package (PQFP)	208	8.0	26.1	22.5	20.8	C/W
Plastic Quad Flat Package (PQFP) with embedded heat spreader in A3PE3000	208	3.8	16.2	13.3	11.9	C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.8	26.9	22.8	21.5	C/W
	484	3.2	20.5	17.0	15.9	C/W
	676	3.2	16.4	13.0	12.0	C/W
	896	2.4	13.6	10.4	9.4	C/W

Temperature and Voltage Derating Factors

Table 2-6 • **Temperature and Voltage Derating Factors for Timing Delays (normalized to T_J = 70°C, VCC = 1.425 V)**

Array Voltage VCC (V)	Junction Temperature (°C)					
	–40°C	0°C	25°C	70°C	85°C	100°C
1.425	0.87	0.92	0.95	1.00	1.02	1.04
1.500	0.83	0.88	0.90	0.95	0.97	0.98
1.575	0.80	0.85	0.87	0.92	0.93	0.95

Guidelines

Toggle Rate Definition

A toggle rate defines the frequency of a net or logic element relative to a clock. It is a percentage. If the toggle rate of a net is 100%, this means that this net switches at half the clock frequency. Below are some examples:

- The average toggle rate of a shift register is 100% as all flip-flop outputs toggle at half of the clock frequency.
- The average toggle rate of an 8-bit counter is 25%:
  - Bit 0 (LSB) = 100%
  - Bit 1 = 50%
  - Bit 2 = 25%
  - …
  - Bit 7 (MSB) = 0.78125%
  - Average toggle rate = (100% + 50% + 25% + 12.5% + . . . + 0.78125%) / 8

Enable Rate Definition

Output enable rate is the average percentage of time during which tristate outputs are enabled. When nontristate output buffers are used, the enable rate should be 100%.

***Table 2-11* • Toggle Rate Guidelines Recommended for Power Calculation**

Component	Definition	Guideline
α_1	Toggle rate of VersaTile outputs	10%
α_2	I/O buffer toggle rate	10%

***Table 2-12* • Enable Rate Guidelines Recommended for Power Calculation**

Component	Definition	Guideline
β_1	I/O output buffer enable rate	100%
β_2	RAM enable rate for read operations	12.5%
β_3	RAM enable rate for write operations	12.5%

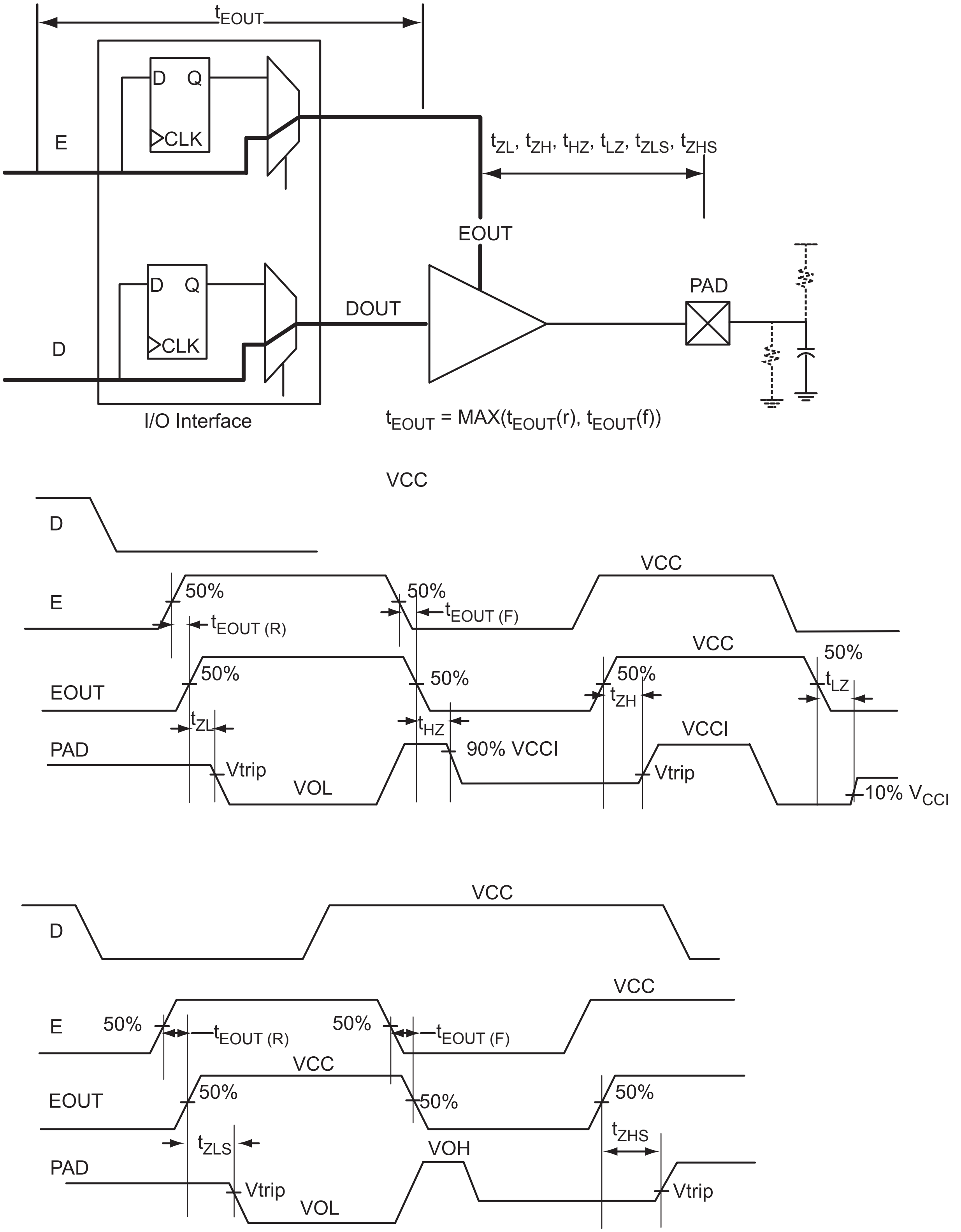


Figure 2-5 • **Tristate Output Buffer Timing Model and Delays (example)**

Single-Ended I/O Characteristics

3.3 V LVTTL / 3.3 V LVCMOS

Low-Voltage Transistor–Transistor Logic is a general-purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTL input buffer and push-pull output buffer. The 3.3 V LVCMOS standard is supported as part of the 3.3 V LVTTL support.

Table 2-25 **• Minimum and Maximum DC Input and Output Levels**

3.3 V LVTTL / 3.3 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL[1]	IIH[2]
Drive Strength	**Min. V**	**Max. V**	**Min., V**	**Max. V**	**Max. V**	**Min. V**	**mA**	**mA**	**Max. mA[3]**	**Max. mA[3]**	**μA[4]**	**μA[4]**
2 mA	–0.3	0.8	2	3.6	0.4	2.4	4	4	27	25	10	10
4 mA	–0.3	0.8	2	3.6	0.4	2.4	4	4	27	25	10	10
6 mA	–0.3	0.8	2	3.6	0.4	2.4	8	8	54	51	10	10
8 mA	–0.3	0.8	2	3.6	0.4	2.4	8	8	54	51	10	10
12 mA	–0.3	0.8	2	3.6	0.4	2.4	12	12	109	103	10	10
16 mA	–0.3	0.8	2	3.6	0.4	2.4	16	16	127	132	10	10
24 mA	–0.3	0.8	2	3.6	0.4	2.4	24	24	181	268	10	10

Notes:

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V< VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN< VCCI. Input current is larger when operating outside recommended ranges.*
3. *Currents are measured at high temperature (100°C junction temperature) and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

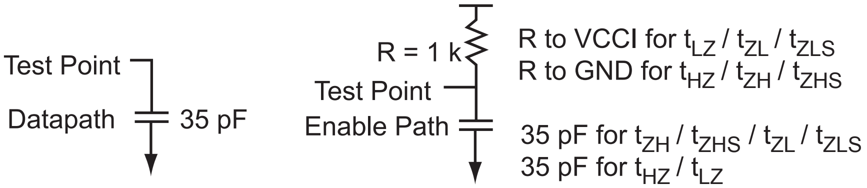


Figure 2-6 **• AC Loading**

Table 2-26 **• 3.3 V LVTTL / 3.3 V LVCMOS AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	C_{LOAD} (pF)
0	3.3	1.4	–	35

Note: *Measuring point = Vtrip. See Table 2-15 on page 2-18 for a complete table of trip points.

SSTL3 Class I

Stub-Speed Terminated Logic for 3.3 V memory bus standard (JESD8-8). ProASIC3E devices support Class I. This provides a differential amplifier input buffer and a push-pull output buffer.

Table 2-72 • Minimum and Maximum DC Input and Output Levels

SSTL3 Class I	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL	IIH
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA[1]	Max. mA[1]	μA[2]	μA[2]
14 mA	–0.3	VREF – 0.2	VREF + 0.2	3.6	0.7	VCCI – 1.1	14	14	54	51	10	10

Notes:

1. *Currents are measured at high temperature (100°C junction temperature) and maximum voltage.*
2. *Currents are measured at 85°C junction temperature.*

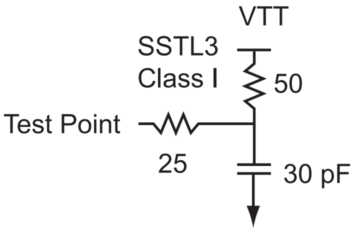


Figure 2-20 • AC Loading

Table 2-73 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	VTT (typ.) (V)	C_{LOAD} (pF)
VREF – 0.2	VREF + 0.2	1.5	1.5	1.485	30

*Note: *Measuring point = Vtrip. See Table 2-15 on page 2-18 for a complete table of trip points.*

Timing Characteristics

Table 2-74 • SSTL3 Class I
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V,
Worst-Case VCCI = 3.0 V, VREF = 1.5 V

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.66	2.31	0.04	1.25	0.43	2.35	1.84			4.59	4.07	ns
–1	0.56	1.96	0.04	1.06	0.36	2.00	1.56			3.90	3.46	ns
–2	0.49	1.72	0.03	0.93	0.32	1.75	1.37			3.42	3.04	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-5 for derating values.

Timing Waveforms

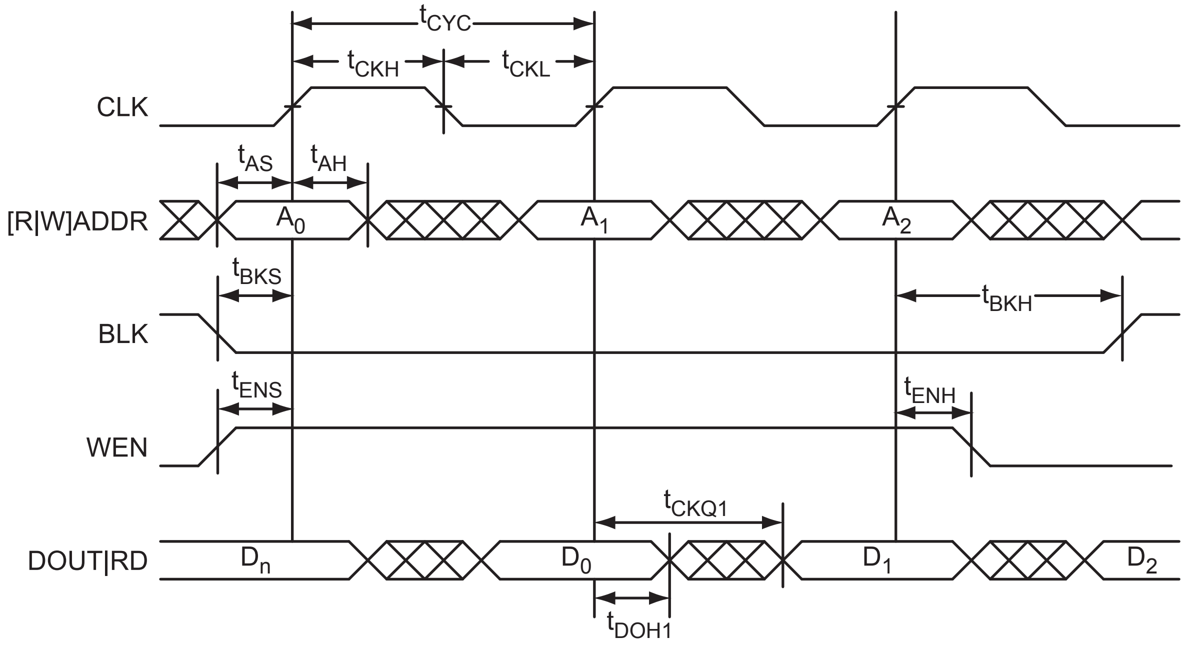


Figure 2-41 • **RAM Read for Pass-Through Output. Applicable to Both RAM4K9 and RAM512x18.**

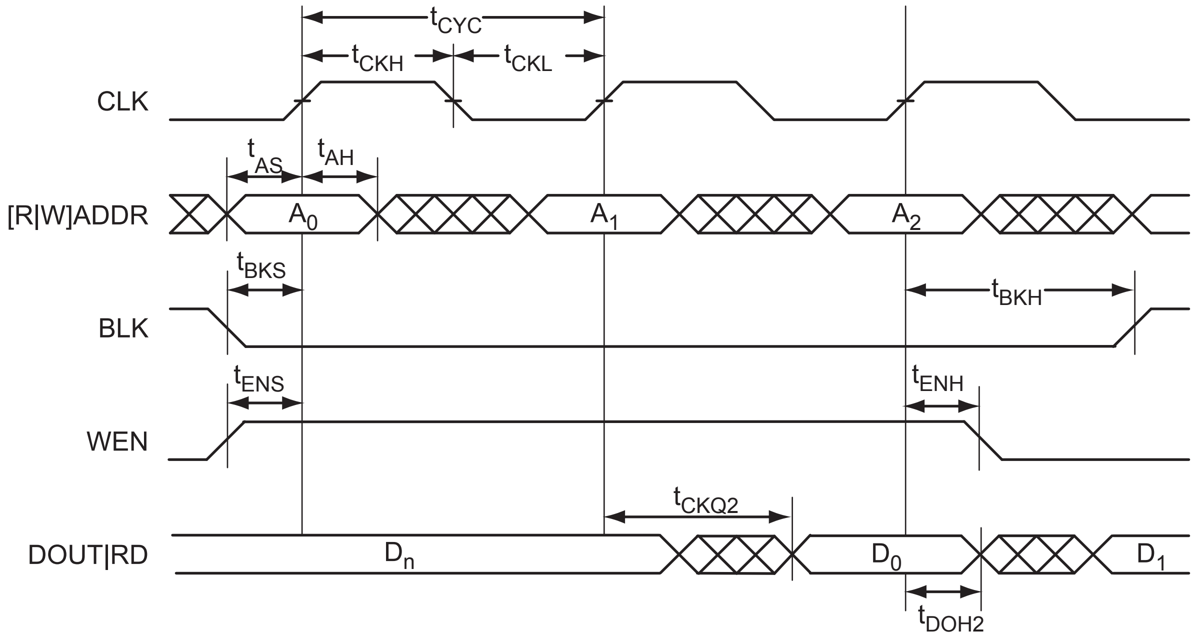


Figure 2-42 • **RAM Read for Pipelined Output. Applicable to Both RAM4K9 and RAM512x18.**

Refer to the I/O Structure section of the *ProASIC3E FPGA Fabric User's Guide* for an explanation of the naming of global pins.

JTAG Pins

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). VCC must also be powered for the JTAG state machine to operate, even if the device is in bypass mode; VJTAG alone is insufficient. Both VJTAG and VCC to the part must be supplied to allow JTAG signals to transition the device. Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND.

TCK Test Clock

Test clock input for JTAG boundary scan, ISP, and UJTAG. The TCK pin does not have an internal pull-up/-down resistor. If JTAG is not used, Microsemi recommends tying off TCK to GND through a resistor placed close to the FPGA pin. This prevents JTAG operation in case TMS enters an undesired state.

Note that to operate at all VJTAG voltages, 500 W to 1 kΩ will satisfy the requirements. Refer to Table 3-1 for more information.

***Table 3-1* • Recommended Tie-Off Values for the TCK and TRST Pins**

VJTAG	Tie-Off Resistance
VJTAG at 3.3 V	200 Ω to 1 kΩ
VJTAG at 2.5 V	200 Ω to 1 kΩ
VJTAG at 1.8 V	500 Ω to 1 kΩ
VJTAG at 1.5 V	500 Ω to 1 kΩ

Notes:

1. *Equivalent parallel resistance if more than one device is on the JTAG chain*
2. *The TCK pin can be pulled up/down.*
3. *The TRST pin is pulled down.*

TDI Test Data Input

Serial input for JTAG boundary scan, ISP, and UJTAG usage. There is an internal weak pull-up resistor on the TDI pin.

TDO Test Data Output

Serial output for JTAG boundary scan, ISP, and UJTAG usage.

TMS Test Mode Select

The TMS pin controls the use of the IEEE 1532 boundary scan pins (TCK, TDI, TDO, TRST). There is an internal weak pull-up resistor on the TMS pin.

TRST Boundary Scan Reset Pin

The TRST pin functions as an active-low input to asynchronously initialize (or reset) the boundary scan circuitry. There is an internal weak pull-up resistor on the TRST pin. If JTAG is not used, an external pull-down resistor could be included to ensure the test access port (TAP) is held in reset mode. The resistor values must be chosen from Table 3-1 and must satisfy the parallel resistance value requirement. The values in Table 3-1 correspond to the resistor recommended when a single device is used, and the equivalent parallel resistor when multiple devices are connected via a JTAG chain.

In critical applications, an upset in the JTAG circuit could allow entrance to an undesired JTAG state. In such cases, Microsemi recommends tying off TRST to GND through a resistor placed close to the FPGA pin.

Note that to operate at all VJTAG voltages, 500 Ω to 1 kΩ will satisfy the requirements.

PQ208	
Pin Number	**A3PE600 Function**
108	TDO
109	TRST
110	VJTAG
111	VMV3
112	GDA0/IO67NPB3V1
113	GDB0/IO66NPB3V1
114	GDA1/IO67PPB3V1
115	GDB1/IO66PPB3V1
116	GDC0/IO65NDB3V1
117	GDC1/IO65PDB3V1
118	IO62NDB3V1
119	IO62PDB3V1
120	IO58NDB3V0
121	IO58PDB3V0
122	GND
123	VCCIB3
124	GCC2/IO55PSB3V0
125	GCB2/IO54PSB3V0
126	NC
127	IO53NDB3V0
128	GCA2/IO53PDB3V0
129	GCA1/IO52PPB3V0
130	GND
131	VCCPLC
132	GCA0/IO52NPB3V0
133	VCOMPLC
134	GCB0/IO51NDB2V1
135	GCB1/IO51PDB2V1
136	GCC1/IO50PSB2V1
137	IO49NDB2V1
138	IO49PDB2V1
139	IO48PSB2V1
140	VCCIB2
141	GND
142	VCC
143	IO47NDB2V1

PQ208	
Pin Number	**A3PE600 Function**
144	IO47PDB2V1
145	IO44NDB2V1
146	IO44PDB2V1
147	IO43NDB2V0
148	IO43PDB2V0
149	IO40NDB2V0
150	IO40PDB2V0
151	GBC2/IO38PSB2V0
152	GBA2/IO36PSB2V0
153	GBB2/IO37PSB2V0
154	VMV2
155	GNDQ
156	GND
157	VMV1
158	GNDQ
159	GBA1/IO35PDB1V1
160	GBA0/IO35NDB1V1
161	GBB1/IO34PDB1V1
162	GND
163	GBB0/IO34NDB1V1
164	GBC1/IO33PDB1V1
165	GBC0/IO33NDB1V1
166	IO31PDB1V1
167	IO31NDB1V1
168	IO27PDB1V0
169	IO27NDB1V0
170	VCCIB1
171	VCC
172	IO23PPB1V0
173	IO22PSB1V0
174	IO23NPB1V0
175	IO21PDB1V0
176	IO21NDB1V0
177	IO19PPB0V2
178	GND
179	IO18PPB0V2

PQ208	
Pin Number	**A3PE600 Function**
180	IO19NPB0V2
181	IO18NPB0V2
182	IO17PPB0V2
183	IO16PPB0V2
184	IO17NPB0V2
185	IO16NPB0V2
186	VCCIB0
187	VCC
188	IO15PDB0V2
189	IO15NDB0V2
190	IO13PDB0V2
191	IO13NDB0V2
192	IO11PSB0V1
193	IO09PDB0V1
194	IO09NDB0V1
195	GND
196	IO07PDB0V1
197	IO07NDB0V1
198	IO05PDB0V0
199	IO05NDB0V0
200	VCCIB0
201	GAC1/IO02PDB0V0
202	GAC0/IO02NDB0V0
203	GAB1/IO01PDB0V0
204	GAB0/IO01NDB0V0
205	GAA1/IO00PDB0V0
206	GAA0/IO00NDB0V0
207	GNDQ
208	VMV0

PQ208	
Pin Number	A3PE1500 Function
1	GND
2	GNDQ
3	VMV7
4	GAB2/IO220PSB7V3
5	GAA2/IO221PDB7V3
6	IO221NDB7V3
7	GAC2/IO219PDB7V3
8	IO219NDB7V3
9	IO215PDB7V3
10	IO215NDB7V3
11	IO212PDB7V2
12	IO212NDB7V2
13	IO208PDB7V2
14	IO208NDB7V2
15	IO204PSB7V1
16	VCC
17	GND
18	VCCIB7
19	IO200PDB7V1
20	IO200NDB7V1
21	IO196PSB7V0
22	GFC1/IO192PSB7V0
23	GFB1/IO191PDB7V0
24	GFB0/IO191NDB7V0
25	VCOMPLF
26	GFA0/IO190NPB6V2
27	VCCPLF
28	GFA1/IO190PPB6V2
29	GND
30	GFA2/IO189PDB6V2
31	IO189NDB6V2
32	GFB2/IO188PPB6V2
33	GFC2/IO187PPB6V2
34	IO188NPB6V2
35	IO187NPB6V2
36	VCC
37	IO184PDB6V2
38	IO184NDB6V2
39	IO180PSB6V1
40	VCCIB6
41	GND
42	IO176PDB6V1
43	IO176NDB6V1
44	GEC1/IO169PDB6V0
45	GEC0/IO169NDB6V0
46	GEB1/IO168PPB6V0
47	GEA1/IO167PPB6V0
48	GEB0/IO168NPB6V0
49	GEA0/IO167NPB6V0
50	VMV6
51	GNDQ
52	GND
53	VMV5
54	GNDQ
55	IO166NDB5V3
56	GEA2/IO166PDB5V3
57	IO165NDB5V3
58	GEB2/IO165PDB5V3
59	IO164NDB5V3
60	GEC2/IO164PDB5V3
61	IO163PSB5V3
62	VCCIB5
63	IO161PSB5V3
64	IO157NDB5V2
65	GND
66	IO157PDB5V2
67	IO153NDB5V2
68	IO153PDB5V2
69	IO149NDB5V1
70	IO149PDB5V1
71	VCC
72	VCCIB5
73	IO145NDB5V1
74	IO145PDB5V1
75	IO143NDB5V1
76	IO143PDB5V1
77	IO137NDB5V0
78	IO137PDB5V0
79	IO135NDB5V0
80	IO135PDB5V0
81	GND
82	IO131NDB4V2
83	IO131PDB4V2
84	IO129NDB4V2
85	IO129PDB4V2
86	IO127NDB4V2
87	IO127PDB4V2
88	VCC
89	VCCIB4
90	IO121NDB4V1
91	IO121PDB4V1
92	IO119NDB4V1
93	IO119PDB4V1
94	IO113NDB4V0
95	GDC2/IO113PDB4V0
96	IO112NDB4V0
97	GND
98	GDB2/IO112PDB4V0
99	GDA2/IO111PSB4V0
100	GNDQ
101	TCK
102	TDI
103	TMS
104	VMV4
105	GND
106	VPUMP
107	GNDQ
108	TDO

FG484	
Pin Number	**A3PE1500 Function**
C21	NC
C22	VCCIB2
D1	NC
D2	NC
D3	NC
D4	GND
D5	GAA0/IO00NDB0V0
D6	GAA1/IO00PDB0V0
D7	GAB0/IO01NDB0V0
D8	IO09PDB0V1
D9	IO13PDB0V1
D10	IO21PDB0V2
D11	IO31NDB0V3
D12	IO37NDB1V0
D13	IO37PDB1V0
D14	IO49NDB1V2
D15	IO49PDB1V2
D16	GBB1/IO56PDB1V3
D17	GBA0/IO57NDB1V3
D18	GBA1/IO57PDB1V3
D19	GND
D20	NC
D21	IO69PDB2V1
D22	NC
E1	NC
E2	IO218PPB7V3
E3	GND
E4	GAB2/IO220PDB7V3
E5	GAA2/IO221PDB7V3
E6	GNDQ
E7	GAB1/IO01PDB0V0
E8	IO09NDB0V1
E9	IO13NDB0V1
E10	IO21NDB0V2
E11	IO31PDB0V3
E12	IO35NDB1V0
E13	IO41NDB1V1
E14	IO41PDB1V1
E15	GBC1/IO55PDB1V3
E16	GBB0/IO56NDB1V3
E17	GNDQ
E18	GBA2/IO58PDB2V0
E19	IO63NDB2V0
E20	GND
E21	IO69NDB2V1
E22	NC
F1	IO218NPB7V3
F2	IO216NDB7V3
F3	IO216PDB7V3
F4	IO220NDB7V3
F5	IO221NDB7V3
F6	VMV7
F7	VCCPLA
F8	GAC0/IO02NDB0V0
F9	GAC1/IO02PDB0V0
F10	IO23NDB0V2
F11	IO23PDB0V2
F12	IO35PDB1V0
F13	IO39NDB1V0
F14	IO45PDB1V1
F15	GBC0/IO55NDB1V3
F16	VCCPLB
F17	VMV2
F18	IO58NDB2V0
F19	IO63PDB2V0
F20	NC
F21	NC
F22	NC
G1	IO211NDB7V2
G2	IO211PDB7V2
G3	NC
G4	IO214PDB7V3
G5	IO217PDB7V3
G6	GAC2/IO219PDB7V3
G7	VCOMPLA
G8	GNDQ
G9	IO19NDB0V2
G10	IO19PDB0V2
G11	IO25PDB0V3
G12	IO33PDB1V0
G13	IO39PDB1V0
G14	IO45NDB1V1
G15	GNDQ
G16	VCOMPLB
G17	GBB2/IO59PDB2V0
G18	IO62PDB2V0
G19	IO62NDB2V0
G20	IO71PDB2V2
G21	IO71NDB2V2
G22	NC
H1	IO209PSB7V2
H2	NC
H3	VCC
H4	IO214NDB7V3
H5	IO217NDB7V3
H6	IO219NDB7V3
H7	IO215PDB7V3
H8	VMV0
H9	VCCIB0
H10	VCCIB0
H11	IO25NDB0V3
H12	IO33NDB1V0
H13	VCCIB1
H14	VCCIB1
H15	VMV1
H16	GBC2/IO60PDB2V0
H17	IO59NDB2V0
H18	IO67NDB2V1

FG676	
Pin Number	**A3PE1500 Function**
C9	IO10PDB0V1
C10	IO16PDB0V2
C11	IO20PDB0V2
C12	IO24PDB0V3
C13	IO23PDB0V2
C14	IO28PDB0V3
C15	IO31PDB0V3
C16	IO32NDB1V0
C17	IO36NDB1V0
C18	IO37NDB1V0
C19	IO45NDB1V1
C20	IO42PPB1V1
C21	IO46NPB1V1
C22	IO48NPB1V2
C23	GBB0/IO56NPB1V3
C24	VMV1
C25	GBC2/IO60PDB2V0
C26	IO60NDB2V0
D1	IO218NDB7V3
D2	IO218PDB7V3
D3	GND
D4	VMV7
D5	IO221NDB7V3
D6	GAC0/IO02NDB0V0
D7	GAC1/IO02PDB0V0
D8	IO05NDB0V0
D9	IO08PDB0V1
D10	IO12NDB0V1
D11	IO18NDB0V2
D12	IO17NDB0V2
D13	IO25NDB0V3
D14	IO29NDB0V3
D15	IO33NDB1V0
D16	IO40PDB1V1
D17	IO43NDB1V1
D18	IO47PDB1V1

FG676	
Pin Number	**A3PE1500 Function**
D19	IO45PDB1V1
D20	IO46PPB1V1
D21	IO48PPB1V2
D22	GBA0/IO57NPB1V3
D23	GNDQ
D24	GBB1/IO56PPB1V3
D25	GBB2/IO59PDB2V0
D26	IO59NDB2V0
E1	IO212PDB7V2
E2	IO211NDB7V2
E3	IO211PDB7V2
E4	IO220NPB7V3
E5	GNDQ
E6	GAB2/IO220PPB7V3
E7	GAB1/IO01PDB0V0
E8	IO05PDB0V0
E9	IO08NDB0V1
E10	IO12PDB0V1
E11	IO18PDB0V2
E12	IO17PDB0V2
E13	IO25PDB0V3
E14	IO29PDB0V3
E15	IO33PDB1V0
E16	IO40NDB1V1
E17	IO43PDB1V1
E18	IO47NDB1V1
E19	IO54NDB1V3
E20	IO52NDB1V2
E21	IO52PDB1V2
E22	VCCPLB
E23	GBA1/IO57PPB1V3
E24	IO63PDB2V0
E25	IO63NDB2V0
E26	IO68PDB2V1
F1	IO212NDB7V2
F2	IO203PPB7V1

FG676	
Pin Number	**A3PE1500 Function**
F3	IO213NDB7V2
F4	IO213PDB7V2
F5	GND
F6	VCCPLA
F7	GAB0/IO01NDB0V0
F8	GNDQ
F9	IO03PDB0V0
F10	IO13PDB0V1
F11	IO15PDB0V1
F12	IO19PDB0V2
F13	IO21PDB0V2
F14	IO27NDB0V3
F15	IO35PDB1V0
F16	IO39NDB1V0
F17	IO51PDB1V2
F18	IO53PDB1V2
F19	IO54PDB1V3
F20	VMV2
F21	VCOMPLB
F22	IO61PDB2V0
F23	IO61NDB2V0
F24	IO66PDB2V1
F25	IO66NDB2V1
F26	IO68NDB2V1
G1	IO203NPB7V1
G2	IO207NDB7V2
G3	IO207PDB7V2
G4	IO216NDB7V3
G5	IO216PDB7V3
G6	VCOMPLA
G7	VMV0
G8	VCC
G9	IO03NDB0V0
G10	IO13NDB0V1
G11	IO15NDB0V1
G12	IO19NDB0V2

FG676	
Pin Number	A3PE1500 Function
G13	IO21NDB0V2
G14	IO27PDB0V3
G15	IO35NDB1V0
G16	IO39PDB1V0
G17	IO51NDB1V2
G18	IO53NDB1V2
G19	VCCIB1
G20	GBA2/IO58PPB2V0
G21	GNDQ
G22	IO64NDB2V1
G23	IO64PDB2V1
G24	IO72PDB2V2
G25	IO72NDB2V2
G26	IO78PDB2V2
H1	IO208NDB7V2
H2	IO208PDB7V2
H3	IO209NDB7V2
H4	IO209PDB7V2
H5	IO219NDB7V3
H6	GAC2/IO219PDB7V3
H7	VCCIB7
H8	VCC
H9	VCCIB0
H10	VCCIB0
H11	VCCIB0
H12	VCCIB0
H13	VCCIB0
H14	VCCIB1
H15	VCCIB1
H16	VCCIB1
H17	VCCIB1
H18	VCCIB1
H19	VCC
H20	VCC
H21	IO58NPB2V0
H22	IO70PDB2V1
H23	IO69PDB2V1
H24	IO76PDB2V2
H25	IO76NDB2V2
H26	IO78NDB2V2
J1	IO197NDB7V0
J2	IO197PDB7V0
J3	VMV7
J4	IO215NDB7V3
J5	IO215PDB7V3
J6	IO214PDB7V3
J7	IO214NDB7V3
J8	VCCIB7
J9	VCC
J10	VCC
J11	VCC
J12	VCC
J13	VCC
J14	VCC
J15	VCC
J16	VCC
J17	VCC
J18	VCC
J19	VCCIB2
J20	IO62PDB2V0
J21	IO62NDB2V0
J22	IO70NDB2V1
J23	IO69NDB2V1
J24	VMV2
J25	IO80PDB2V3
J26	IO80NDB2V3
K1	IO195PDB7V0
K2	IO199NDB7V1
K3	IO199PDB7V1
K4	IO205NDB7V1
K5	IO205PDB7V1
K6	IO217PDB7V3
K7	IO217NDB7V3
K8	VCCIB7
K9	VCC
K10	GND
K11	GND
K12	GND
K13	GND
K14	GND
K15	GND
K16	GND
K17	GND
K18	VCC
K19	VCCIB2
K20	IO65PDB2V1
K21	IO65NDB2V1
K22	IO74PDB2V2
K23	IO74NDB2V2
K24	IO75PDB2V2
K25	IO75NDB2V2
K26	IO84PDB2V3
L1	IO195NDB7V0
L2	IO198PPB7V0
L3	GNDQ
L4	IO201PDB7V1
L5	IO201NDB7V1
L6	IO210NDB7V2
L7	IO210PDB7V2
L8	VCCIB7
L9	VCC
L10	GND
L11	GND
L12	GND
L13	GND
L14	GND
L15	GND
L16	GND

FG676	
Pin Number	**A3PE1500 Function**
W25	IO96PDB3V1
W26	IO94NDB3V0
Y1	IO175NDB6V1
Y2	IO175PDB6V1
Y3	IO173NDB6V0
Y4	IO173PDB6V0
Y5	GEC1/IO169PPB6V0
Y6	GNDQ
Y7	VMV6
Y8	VCCIB5
Y9	IO163NDB5V3
Y10	IO159PDB5V3
Y11	IO153PDB5V2
Y12	IO147PDB5V1
Y13	IO139PDB5V0
Y14	IO137PDB5V0
Y15	IO125NDB4V1
Y16	IO125PDB4V1
Y17	IO115NDB4V0
Y18	IO115PDB4V0
Y19	VCC
Y20	VPUMP
Y21	VCOMPLD
Y22	VCCPLD
Y23	IO100NDB3V1
Y24	IO100PDB3V1
Y25	IO96NDB3V1
Y26	IO98PDB3V1

Revision	Changes	Page
Revision 11 (August 2012)	Added a Note stating "VMV pins must be connected to the corresponding VCCI pins. See the "VMVx I/O Supply Voltage (quiet)" section on page 3-1 for further information." to Table 2-1 • Absolute Maximum Ratings and Table 2-2 • Recommended Operating Conditions [1] (SAR 38322).	2-1 3-1 2-1
	The drive strength, IOL, and IOH value for 3.3 V GTL and 2.5 V GTL was changed from 25 mA to 20 mA in the following tables (SAR 31924): "Summary of Maximum and Minimum DC Input and Output Levels" table "Summary of I/O Timing Characteristics—Software Default Settings" table "I/O Output Buffer Maximum Resistances[1]" table "Minimum and Maximum DC Input and Output Levels" table) "Minimum and Maximum DC Input and Output Levels" table Also added note stating "Output drive strength is below JEDEC specification" for Tables 2-17 and 2-19. Additionally, the IOL and IOH values for 3.3 V GTL+ and 2.5 V GTL+ were corrected from 51 to 35 (for 3.3 V GTL+) and from 40 to 33 (for 2.5 V GTL+) in table Table 2-13 (SAR 39714).	2-16 2-19 2-20 2-39 2-40
	"Duration of Short Circuit Event Before Failure" table was revised to change the maximum temperature from 110°C to 100°C, with an example of six months instead of three months (SAR 37934).	2-22
	The following sentence was deleted from the "2.5 V LVCMOS" section (SAR 34796): "It uses a 5 V–tolerant input buffer and push-pull output buffer." This change was made in revision 10 and omitted from the change table in error.	2-30
Revision 11 (continued)	Figure 2-11 was updated to match tables in the "Summary of I/O Timing Characteristics – Default I/O Software Settings" section (SAR 34889).	2-38
	In Table 2-81 VIL and VIH were revised so that the maximum is 3.6 V for all listed values of VCCI (SAR 37222).	2-52
	Figure 2-47and Figure 2-48 are new (SAR 34848).	2-79
	The following sentence was removed from the "VMVx I/O Supply Voltage (quiet)" section in the "Pin Descriptions and Packaging" chapter: "Within the package, the VMV plane is decoupled from the simultaneous switching noise originating from the output buffer VCCI domain" and replaced with “Within the package, the VMV plane biases the input stage of the I/Os in the I/O banks” (SAR 38322). The datasheet mentions that "VMV pins must be connected to the corresponding VCCI pins" for an ESD enhancement.	3-1

Revision	Changes	Page
Advance v0.5 (continued)	The "RESET" section was updated.	2-25
	The "RESET" section was updated.	2-27
	The "Introduction" of the "Introduction" section was updated.	2-28
	PCI-X 3.3 V was added to the Compatible Standards for 3.3 V in Table 2-11 • VCCI Voltages and Compatible Standards	2-29
	Table 2-35 • ProASIC3E I/O Features was updated.	2-54
	The "Double Data Rate (DDR) Support" section was updated to include information concerning implementation of the feature.	2-32
	The "Electrostatic Discharge (ESD) Protection" section was updated to include testing information.	2-35
	Level 3 and 4 descriptions were updated in Table 2-43 • I/O Hot-Swap and 5 V Input Tolerance Capabilities in ProASIC3 Devices.	2-64
	The notes in Table 2-45 • I/O Hot-Swap and 5 V Input Tolerance Capabilities in ProASIC3E Devices were updated.	2-64
	The "Simultaneous Switching Outputs (SSOs) and Printed Circuit Board Layout" section is new.	2-41
	A footnote was added to Table 2-37 • Maximum I/O Frequency for Single-Ended and Differential I/Os in All Banks in ProASIC3E Devices (maximum drive strength and high slew selected).	2-55
	Table 2-48 • ProASIC3E I/O Attributes vs. I/O Standard Applications	2-81
	Table 2-55 • ProASIC3 I/O Standards—SLEW and Output Drive (OUT_DRIVE) Settings	2-85
	The "x" was updated in the "Pin Descriptions" section.	2-50
	The "VCC Core Supply Voltage" pin description was updated.	2-50
	The "VMVx I/O Supply Voltage (quiet)" pin description was updated to include information concerning leaving the pin unconnected.	2-50
	EXTFB was removed from Figure 2-24 • ProASIC3E CCC Options.	2-24
	The CCC Output Peak-to-Peak Period Jitter F_{CCC_OUT} was updated in Table 2-13 • ProASIC3E CCC/PLL Specification.	2-30
	EXTFB was removed from Figure 2-27 • CCC/PLL Macro.	2-28
	The LVPECL specification in Table 2-45 • I/O Hot-Swap and 5 V Input Tolerance Capabilities in ProASIC3E Devices was updated.	2-64
	Table 2-15 • Levels of Hot-Swap Support was updated.	2-34
	The "Cold-Sparing Support" section was updated.	2-34
	"Electrostatic Discharge (ESD) Protection" section was updated.	2-35
	The VJTAG and I/O pin descriptions were updated in the "Pin Descriptions" section.	2-50
	The "VJTAG JTAG Supply Voltage" pin description was updated.	2-50
	The "VPUMP Programming Supply Voltage" pin description was updated to include information on what happens when the pin is tied to ground.	2-50

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "ProASIC3E Device Status" table on page II, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Production

This version contains information that is considered to be final.

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